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[Bergquist](#)
[Q3-0.005-00-05](#)

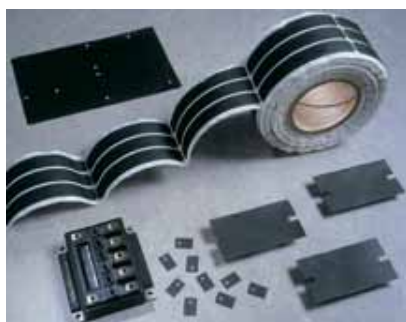
For any questions, you can email us directly:
sales@integrated-circuit.com

Q-Pad® 3

Glass-Reinforced Grease Replacement Thermal Interface

Features and Benefits

- Thermal impedance: 0.35°C-in²/W (@50 psi)
- Eliminates processing constraints typically associated with grease
- Conforms to surface textures
- Easy handling
- May be installed prior to soldering and cleaning without worry



Bergquist Q-Pad 3 eliminates problems associated with thermal grease such as contamination of electronic assemblies and reflow solder baths. Q-Pad 3 may be installed prior to soldering and cleaning without worry. When clamped between two surfaces, the elastomer conforms to surface textures thereby creating an air-free interface between heat-generating components and heat sinks.

Fiberglass reinforcement enables Q-Pad 3 to withstand processing stresses without losing physical integrity. It also provides ease of handling during application.

TYPICAL PROPERTIES OF Q-PAD 3						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Black	Black	Visual			
Reinforcement Carrier	Fiberglass	Fiberglass	—			
Thickness (inch) / (mm)	0.005	0.127	ASTM D374			
Hardness (Shore A)	86	86	ASTM D2240			
Continuous Use Temp (°F) / (°C)	-76 to 356	-60 to 180	—			
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	Non-Insulating	Non-Insulating	ASTM D149			
Dielectric Constant (1000 Hz)	NA	NA	ASTM D150			
Volume Resistivity (Ohm-meter)	10 ²	10 ²	ASTM D257			
Flame Rating	V-O	V-O	U.L.94			
THERMAL						
Thermal Conductivity (W/m-K)	2.0	2.0	ASTM D5470			
THERMAL PERFORMANCE vs PRESSURE						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		2.26	1.99	1.76	1.53	1.30
Thermal Impedance (°C-in²/W) (1)		0.65	0.48	0.35	0.24	0.16

1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

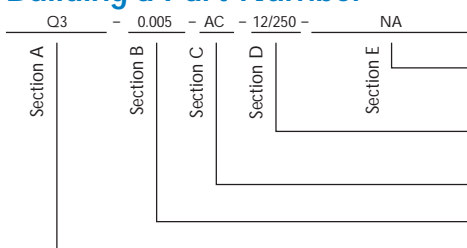
Typical Applications Include:

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

Configurations Available:

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

Building a Part Number



Standard Options

◀ example
 NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.
 — = Standard configuration dash number, 1212 = 12" x 12" sheets, 12/250 = 12" x 250' rolls, or 00 = custom configuration
 AC = Adhesive, one side
 00 = No adhesive
 Standard thicknesses available: 0.005"
 Q3 = Q-Pad 3 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others